Product Change Notification: KSRA-07JMKW160

Date:

27-Mar-2019

Product Category:

16-Bit Microcontrollers, 32-Bit Microcontrollers, 8-Bit Microcontrollers, Digital Signal Controllers

Notification Subject:

CCB 3499 and 3499.001 Final Notice: Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um, 90nm TSMC, 160K and 200K wafer technologies available in 64L TQFP (14x14x1mm) and 100L TQFP (14x14x1mm) packages.

Affected CPNs:

KSRA-07JMKW160_Affected_CPN_03272019.pdf
KSRA-07JMKW160_Affected_CPN_03272019.csv

Notification Text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um, 90nm TSMC, 160K and 200K wafer technologies available in 64L TQFP (14x14x1mm) and 100L TQFP (14x14x1mm) packages.

Pre Change:
Assembled at ASAC using gold (Au) bond wire, 2200 die attach, G700 molding compound and C7025 lead frame material. Assembled at ANAP using gold (Au) bond wire, 3230 or AP4200 die attach, G700 or G631HQ molding compound and C194 lead frame material. Assembled at ASE using palladium coated copper (PdCu) bond wire, 1076WA die attach, G631H molding compound and C7025 lead frame material.

Post Change:
Assembled at ASAC using gold (Au) bond wire, 2200 die attach, G700 molding compound and C7025 lead frame material.

Assembled at ANAP using gold (Au) bond wire, 3230 or AP4200 die attach, G700 or G631HQ molding compound and C194 lead frame material. Assembled at ASE using palladium coated copper (PdCu) bond wire, 1076WA die attach, G631H molding compound and C7025 lead frame material. Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound and C7025 lead frame material.

Pre and Post Change Summary:

	Pre Change				**Post Change**				
Assembly Site	UTAC Dongguan Ltd (P1) / ASAC	Amkor Technology Philippine (P1/P2), INC. / ANAP		ASE Inc. / ASE	UTAC Dongguan Ltd (P1) / ASAC	Amkor Technology Philippine (P1/P2), INC. / ANAP		ASE Inc. / ASE	Microchip Technology Thailand (Branch) / MMT
Wire material	Au	Au		PdCu	Au	Au		PdCu	Au
Die attach material	2200	3230	AP4200	1076WA	2200	3230	AP4200	1076WA	3280
Molding compound material	G700	G700	G631HQ	G631H	G700	G700	G631HQ	G631H	G700
Lead frame material	C7025	C194		C7025	C7025	C194		C7025	C7025
MSL	L3/260C	L3/260C		L3/260C	L3/260C	L3/260C		L3/260C	L3/260C

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve on-time delivery performance by qualifying MMT as a new assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
For 100L TQFP package: January 11, 2019 (date code: 1902)
For 64L TQFP package: March 30, 2019 (date code: 1913)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2018					->	**December 2018**				**January 2019**					->	**March 2019**			
Workweek	31	32	33	34	35		49	50	51	52	01	02	03	04	05		10	11	12	13
Initial PCN Issue Date		X																		
Qual Report Availability							X													

Final PCN Issue Date							X													
Estimated Implementation Date												X								X*

***For 64L TQFP package**

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:
August 09, 2018: Issued initial notification.
December 11, 2018: Issued final notification. Attached is the qualification report. Added estimated first ship date by January 11, 2019.
March 8, 2019: Re-issued final notification to update the subject and description because of the update in scope to include products of 0.25um TSMC and 160K wafer technologies available in 64L TQFP package. Updated the affected CPN list in accordance with the update to the scope. Updated the pre and post change summary table MSL classification for MMT site from MSL 1 and 2 to MSL 3. Updated the pre and post change to add AP4200 die attach material and G631HQ mold compound material for ANAP assembly site which is applicable for 64L TQFP package.
March 27, 2019: Corrected the estimated first ship date year for 100L TQFP from 2018 to 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_KSRA-07JMKW160_Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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